

### The Embedded I/O Company

# **TIP250**

## 8 Mbytes Flash Memory

Version 1.0

### **User Manual**

Issue 1.2 October 2008



#### **TIP250-10**

8 Mbytes Flash Memory

This document contains information, which is proprietary to TEWS TECHNOLOGIES GmbH. Any reproduction without written permission is forbidden.

TEWS TECHNOLOGIES GmbH has made any effort to ensure that this manual is accurate and complete. However TEWS TECHNOLOGIES GmbH reserves the right to change the product described in this document at any time without notice.

TEWS TECHNOLOGIES GmbH is not liable for any damage arising out of the application or use of the device described herein.

#### **Style Conventions**

Hexadecimal characters are specified with prefix 0x, i.e. 0x029E (that means hexadecimal value 029E).

For signals on hardware products, an ,Active Low' is represented by the signal name with # following, i.e. IP\_RESET#.

Access terms are described as:

W Write Only
R Read Only
R/W Read/Write
R/C Read/Clear
R/S Read/Set

©2001 -2008 by TEWS TECHNOLOGIES GmbH

All trademarks mentioned are property of their respective owners.



Issue	Description	Date
1.0	First Issue	December 2001
1.1	Added MTBF Value	January 2002
1.2	Added Weight New Address TEWS LLC	October 2008



## **Table of Contents**

1	PRODUCT DESCRIPTION	6
2	TECHNICAL SPECIFICATION	7
	ID PROM CONTENTS	
	IP ADDRESSING	
	4.1 I/O Addressing	9
	4.1.1 Flash Control Register (FCR)	g
	4.1.2 Flash Status Register (FSR)	10
	4.1.3 Interrupt Vector Register (IVR)	10
	4.2 Memory Addressing	10
5	HINTS	11
	5.1 Flash Memory	11
	5.2 JTAG Connector	11



## **Table of Figures**

FIGURE 1-1:	BLOCK DIAGRAM	6
FIGURE 2-1 :	TECHNICAL SPECIFICATION	7
FIGURE 3-1 :	ID PROM CONTENTS	8
FIGURE 4-1 :	REGISTER SET	9
FIGURE 4-2 :	FLASH CONTROL REGISTER	9
FIGURE 4-3:	FLASH STATUS REGISTER	10
FIGURE 4-4 :	INTERRUPT VECTOR REGISTER	10
FIGURE 4-5 :	MEMORY STRUCTURE	10
FIGURE 5-1 :	TYPICAL FLASH ACCESS TIMES	11
FIGURE 5-2 :	JTAG CONNECTOR	11



## 1 Product Description

The TIP250 is an IndustryPack compatible module that offers an easy and reliable way to implement 8 Mbytes of Flash memory. The TIP250 is ideal for holding application code, operating system software or data.

Two AM29LV033 devices (32 Mbit, x 8 organized) are used to provide 1 bank of 8 Mbytes (16 bit wide) Flash memory, which is divided, into 64 sectors of 128 Kbytes (16 bit wide).

Access to the TIP250 Flash memory occurs within the IP memory space. After power-on the TIP250 starts up in read only mode. The IP I/O space holds the Flash Control Register, the Flash Status Register and the Interrupt Vector Register.

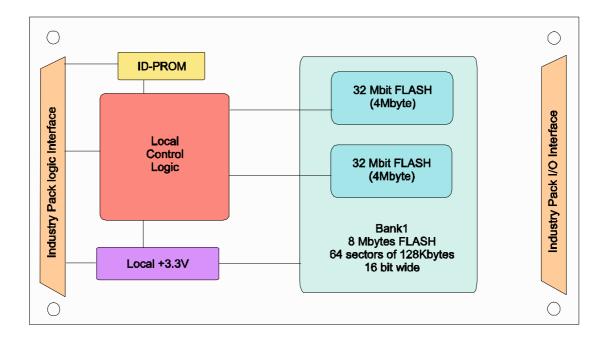


Figure 1-1: Block Diagram



# 2 Technical Specification

Interface						
ID ROM Data Format I  WO Space Used, with no wait states Memory Space 8 MByte, with 1 wait state Interrupts Only INTREQ0# is used  DMA Not supported Clock Rate 8 MHz  Module Type Type I  On Board Devices  Memory  8 MBytes Flash Memory (4 Mbit x 16), implemented by two AM29LV033 (or compatible). Organized as 64 sectors of 128 KBytes Min. erase and program cycle endurance: 1 000 000  WO Interface no connection to the IP I/O connector  Power Requirements 160 mA typical @ +5V DC  Physical Data  Temperature Range Operating -40 °C to +85 °C -55 °C to +125 °C Storage -55 °C to +125 °C  MTBF  407000 h  MTBF values shown are based on calculation according to MIL-HDBK-217F and MIL-HDBK-217F Notice 2; Environment: G <sub>B</sub> 20 °C. The MTBF calculation is based on component FIT rates provided by the component suppliers. If FIT rates are not available, MIL-HDBK-217F and MIL-HDBK-217F Notice 2 formulas are used for FIT rate calculation.	IP Interface	IP Interface				
Memory Space Used, with no wait states  Memory Space 8 MByte, with 1 wait state  Interrupts Only INTREQ0# is used  DMA Not supported  Clock Rate 8 MHz  Module Type Type I  On Board Devices  Memory 8 MBytes Flash Memory (4 Mbit x 16), implemented by two AM29LV033 (or compatible). Organized as 64 sectors of 128 KBytes Min. erase and program cycle endurance: 1 000 000  I/O Interface  no connection to the IP I/O connector  Power Requirements 160 mA typical @ +5V DC  Physical Data  Temperature Range Operating Storage Storage -55°C to +125°C  MTBF 407000 h  MTBF values shown are based on calculation according to MIL-HDBK-217F and MIL-HDBK-217F Notice 2; Environment: G <sub>B</sub> 20°C.  The MTBF calculation is based on component FIT rates provided by the component suppliers. If FIT rates are not available, MIL-HDBK-217F and MIL-HDBK-217F Notice 2 formulas are used for FIT rate calculation.	Interface					
Memory Space   8 MByte, with 1 wait state	ID ROM Data	Format I				
Interrupts  Only INTREQ0# is used  DMA  Not supported  Clock Rate  8 MHz  Module Type  Type I  On Board Devices  Memory  8 MBytes Flash Memory (4 Mbit x 16), implemented by two AM29LV033 (or compatible).  Organized as 64 sectors of 128 KBytes Min. erase and program cycle endurance: 1 000 000  I/O Interface  no connection to the IP I/O connector  Power Requirements  160 mA typical @ +5V DC  Physical Data  Temperature Range  Operating	I/O Space	Used, with r	no wait states			
DMA Not supported  Clock Rate 8 MHz  Module Type Type I  On Board Devices  Memory 8 MBytes Flash Memory (4 Mbit x 16), implemented by two AM29LV033 (or compatible). Organized as 64 sectors of 128 KBytes Min. erase and program cycle endurance: 1 000 000  I/O Interface  no connection to the IP I/O connector  Power Requirements 160 mA typical @ +5V DC  Physical Data  Temperature Range Operating -40 °C to +85 °C Storage -55°C to +125°C  MTBF 407000 h MTBF values shown are based on calculation according to MIL-HDBK-217F and MIL-HDBK-217F Notice 2; Environment: G <sub>B</sub> 20°C. The MTBF calculation is based on component FIT rates provided by the component suppliers. If FIT rates are not available, MIL-HDBK-217F and MIL-HDBK-217F Notice 2 formulas are used for FIT rate calculation.	Memory Space	8 MByte, wit	th 1 wait state			
Clock Rate 8 MHz  Module Type Type I  On Board Devices  Memory 8 MBytes Flash Memory (4 Mbit x 16), implemented by two AM29LV033 (or compatible). Organized as 64 sectors of 128 KBytes Min. erase and program cycle endurance: 1 000 000  I/O Interface  no connection to the IP I/O connector  Power Requirements 160 mA typical @ +5V DC  Physical Data  Temperature Range Operating -40 °C to +85 °C Storage -55°C to +125°C  MTBF 407000 h  MTBF values shown are based on calculation according to MIL-HDBK-217F and MIL-HDBK-217F Notice 2; Environment: G <sub>B</sub> 20°C. The MTBF calculation is based on component FIT rates provided by the component suppliers. If FIT rates are not available, MIL-HDBK-217F and MIL-HDBK-217F Notice 2 formulas are used for FIT rate calculation.	Interrupts	Only INTRE	Q0# is used			
Module Type  Type I  On Board Devices  Memory  8 MBytes Flash Memory (4 Mbit x 16), implemented by two AM29LV033 (or compatible). Organized as 64 sectors of 128 KBytes Min. erase and program cycle endurance: 1 000 000  I/O Interface  no connection to the IP I/O connector  Power Requirements  160 mA typical @ +5V DC  Physical Data  Temperature Range  Operating	DMA	Not support	ed			
On Board Devices  Memory  8 MBytes Flash Memory (4 Mbit x 16), implemented by two AM29LV033 (or compatible). Organized as 64 sectors of 128 KBytes Min. erase and program cycle endurance: 1 000 000  I/O Interface  no connection to the IP I/O connector  Power Requirements  160 mA typical @ +5V DC  Physical Data  Temperature Range  Operating	Clock Rate	8 MHz				
Memory  8 MBytes Flash Memory (4 Mbit x 16), implemented by two AM29LV033 (or compatible).  Organized as 64 sectors of 128 KBytes Min. erase and program cycle endurance: 1 000 000  I/O Interface  no connection to the IP I/O connector  Power Requirements  160 mA typical @ +5V DC  Physical Data  Temperature Range  Operating	Module Type	Type I				
AM29LV033 (or compatible). Organized as 64 sectors of 128 KBytes Min. erase and program cycle endurance: 1 000 000  I/O Interface  no connection to the IP I/O connector  Power Requirements  160 mA typical @ +5V DC  Physical Data  Temperature Range  Operating	On Board Devices					
Min. erase and program cycle endurance: 1 000 000  I/O Interface  no connection to the IP I/O connector  Power Requirements 160 mA typical @ +5V DC  Physical Data  Temperature Range Operating -40 °C to +85 °C -55°C to +125°C  MTBF 407000 h  MTBF values shown are based on calculation according to MIL-HDBK-217F and MIL-HDBK-217F Notice 2; Environment: G <sub>B</sub> 20°C.  The MTBF calculation is based on component FIT rates provided by the component suppliers. If FIT rates are not available, MIL-HDBK-217F and MIL-HDBK-217F Notice 2 formulas are used for FIT rate calculation.	Memory					
I/O Interface  no connection to the IP I/O connector  Power Requirements 160 mA typical @ +5V DC  Physical Data  Temperature Range Operating -40 °C to +85 °C -55 °C to +125 °C  MTBF 407000 h  MTBF values shown are based on calculation according to MIL-HDBK-217F and MIL-HDBK-217F Notice 2; Environment: G <sub>B</sub> 20 °C.  The MTBF calculation is based on component FIT rates provided by the component suppliers. If FIT rates are not available, MIL-HDBK-217F and MIL-HDBK-217F Notice 2 formulas are used for FIT rate calculation.		U	•			
no connection to the IP I/O connector  Power Requirements 160 mA typical @ +5V DC  Physical Data  Temperature Range Operating -40 °C to +85 °C Storage -55 °C to +125 °C  MTBF 407000 h  MTBF values shown are based on calculation according to MIL-HDBK-217F and MIL-HDBK-217F Notice 2; Environment: G <sub>B</sub> 20 °C.  The MTBF calculation is based on component FIT rates provided by the component suppliers. If FIT rates are not available, MIL-HDBK-217F and MIL-HDBK-217F Notice 2 formulas are used for FIT rate calculation.		Min. erase and program cycle endurance: 1 000 000				
Power Requirements  160 mA typical @ +5V DC  Physical Data  Temperature Range  Operating -40 °C to +85 °C -55°C to +125°C  MTBF  407000 h  MTBF values shown are based on calculation according to MIL-HDBK-217F and MIL-HDBK-217F Notice 2; Environment: G <sub>B</sub> 20°C.  The MTBF calculation is based on component FIT rates provided by the component suppliers. If FIT rates are not available, MIL-HDBK-217F and MIL-HDBK-217F Notice 2 formulas are used for FIT rate calculation.	I/O Interface					
Physical Data  Temperature Range  Operating	no connection to the IP I/O connector					
Physical Data  Temperature Range  Operating						
Temperature Range  Operating Storage  -40 °C to +85 °C  -55°C to +125°C  MTBF  407000 h  MTBF values shown are based on calculation according to MIL-HDBK-217F and MIL-HDBK-217F Notice 2; Environment: G <sub>B</sub> 20°C.  The MTBF calculation is based on component FIT rates provided by the component suppliers. If FIT rates are not available, MIL-HDBK-217F and MIL-HDBK-217F Notice 2 formulas are used for FIT rate calculation.	Power Requirements	160 mA typi	cal @ +5V DC			
Storage -55°C to +125°C  MTBF  407000 h  MTBF values shown are based on calculation according to MIL-HDBK-217F and MIL-HDBK-217F Notice 2; Environment: G <sub>B</sub> 20°C.  The MTBF calculation is based on component FIT rates provided by the component suppliers. If FIT rates are not available, MIL-HDBK-217F and MIL-HDBK-217F Notice 2 formulas are used for FIT rate calculation.	Physical Data					
MTBF  407000 h  MTBF values shown are based on calculation according to MIL-HDBK-217F and MIL-HDBK-217F Notice 2; Environment: G <sub>B</sub> 20°C.  The MTBF calculation is based on component FIT rates provided by the component suppliers. If FIT rates are not available, MIL-HDBK-217F and MIL-HDBK-217F Notice 2 formulas are used for FIT rate calculation.	Temperature Range	Operating	-40 °C to +85 °C			
MTBF values shown are based on calculation according to MIL-HDBK-217F and MIL-HDBK-217F Notice 2; Environment: G <sub>B</sub> 20°C.  The MTBF calculation is based on component FIT rates provided by the component suppliers. If FIT rates are not available, MIL-HDBK-217F and MIL-HDBK-217F Notice 2 formulas are used for FIT rate calculation.		Storage -55°C to +125°C				
Humidity 5 – 95 % non-condensing	MTBF	MTBF values shown are based on calculation according to MIL-HDBK-217F and MIL-HDBK-217F Notice 2; Environment: G <sub>B</sub> 20°C.  The MTBF calculation is based on component FIT rates provided by the component suppliers. If FIT rates are not available, MIL-HDBK-217F and				
	Humidity	5 – 95 % non-condensing				
Weight 25 g	Weight	25 g				

Figure 2-1: Technical Specification



## 3 ID PROM Contents

Address	Function	Contents
0x01	ASCII 'I'	0x49
0x03	ASCII 'P'	0x50
0x05	ASCII 'A'	0x41
0x07	ASCII 'C'	0x43
0x09	Manufacturer ID	0xB3
0x0B	Model Number	0x30
0x0D	Revision	0x10
0x0F	Reserved	0x00
0x11	Driver-ID Low - Byte	0x00
0x13	Driver-ID High - Byte	0x00
0x15	Number of bytes used	0x0C
0x17	CRC	0xFD

Figure 3-1: ID PROM Contents



## 4 IP Addressing

The control registers of the TIP250 are accessible in the IP I/O Space.

The Flash memory of the TIP250 is accessible in the IP MEM Space.

## 4.1 I/O Addressing

The complete register set of the TIP250 is accessible in the I/O space of the IP.

Address	Symbol	Description	Size (Bit)	Access
0x01	FCR	Flash Control Register	8	R/W
0x03	FSR	Flash Status Register	8	R/W
0x05	IVR	Interrupt Vector Register	8	R/W

Figure 4-1: Register Set

#### 4.1.1 Flash Control Register (FCR)

Read/Write Register to control basic features of the TIP250.

Bit	Symbol	Description	Access	Reset Value
7	F_RST	Reset flash memory Writing a "1" forces the Flash Memory into reset. A subsequently written "0" terminates the reset. Reset forces the flash memory into read-only state. Refer to the AM29LV033 data sheet for more details.	R/W	0
6	WP	Write Protect (active high)  0 = no write protection  1 = write protected (default after Reset)	R/W	1
5	INT_EN	Interrupt Enable  0 = interrupt disabled  1 = An interrupt is generated on IP INTREQ0# when the flash memory's state changes from BUSY to READY during WRITE or ERASE commands.  Any write to the FSR clears the pending interrupt.	R	0
4:0	-	reserved	R	-

Figure 4-2: Flash Control Register



### 4.1.2 Flash Status Register (FSR)

Read/Write register. A read displays status information. Any write to the FSR clears the pending interrupt.

Bit	Symbol	Description	Access	Reset Value
7:6	-	reserved	R	-
5	INTSTAT	Interrupt Status 0 = no pending interrupt 1 = interrupt is pending	R	0
4	RDY/BSY#	Flash Ready / Busy# signal if the flash devices 0 = Flash is busy 1 = Flash is ready	R	1
3:0	-	reserved	R	-

Figure 4-3: Flash Status Register

#### 4.1.3 Interrupt Vector Register (IVR)

Read/Write register. This register is cleared automatically during IP Reset. The Interrupt Vector must be loaded by software.

Bit	Symbol	Description	Access	Reset Value
7:0	INTVEC	Interrupt Vector loaded by software	R/W	0x00

Figure 4-4: Interrupt Vector Register

### 4.2 Memory Addressing

Two AM29LV033 devices (each organized as 32 Mbit x 8) are used to provide 1 bank of 8 Mbytes (16 bit wide) Flash memory, which is divided into 64 sectors of 128 Kbytes (16 bit wide). Access to the TIP250 Flash memory occurs within the IP memory space. Refer to AM29LV033 datasheet for command sequence details.

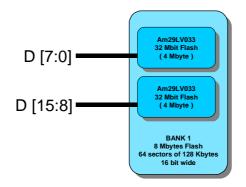


Figure 4-5: Memory Structure



## 5 Hints

No Configuration like e.g. Jumper setting is necessary for the TIP250.

## 5.1 Flash Memory

The 8 MByte (4 MBit x 16) Flash Memory of the TIP250 is implemented by two AM29LV033 (or compatible) Flash devices.

Typical access times:

Bank erase time	typ. 45 s
Sector erase time	typ. 0.7 s
Word programming time	typ. 9 µs
Bank programming time	typ. 36 s

Figure 5-1: typical Flash access times

### 5.2 JTAG Connector

For factory programming of the on board CPLD, the TIP250 has a JTAG connector.

This connector is only for factory use. See figure below for location of the JTAG connector.

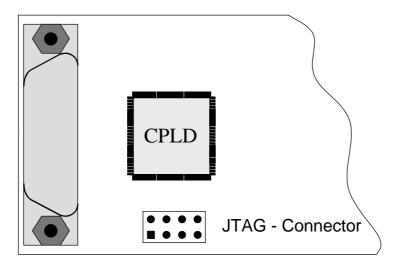


Figure 5-2: JTAG Connector